Resistors



Metal Glaze™ High Power Density **Surface Mount Power Resistor**

MRC Series

- 1/2 watt in 1/8 watt package
- MRC1/2: 0.05Ω to 1.0Ω (contact factory for higher values)
- 150°C maximum operating temperature
- Superior surge handling capability
- RoHS compliant Versions available

OBSOLETE



All Pb-free parts comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Electrical Data

| Size Code ¹ | Industry Footprint | IRC Type | Max. Power Rating | Working Voltage ² | Max. Voltage | Resistance Range (ohms) ³ | Tolerance (±%) ³ | TCR (ppm/°C) ³ | Product Catagory |
|---------------------------|-----------------------|-------------|----------------------|---------------------------------|-----------------|---|--------------------------------|------------------------------|---------------------|
| С | 1206 | MRC1/2 | 1/2W @ 70°C | 200 | 400 | 0.1 to 0.99 | 1,2,5 | 100 | Low Range |
| | | | | | | 1.0 to 10K | 1,2,5 | 50,100 | Standard |
| | | | | | | 20 to 10K | 0.25, 0.5 | 50,100 | Tight Tolerance |

MRC Applications:

The MRC1/2 will dissipate 1/2 watt at 70°C on a 1206 footprint. The MRC is recommended for applications where board real estate is a major concern. Due to high power density and superior surge handling capability, it is also recommended as a direct replacement on existing board designs where standard 1206 resistors are marginal or failing.

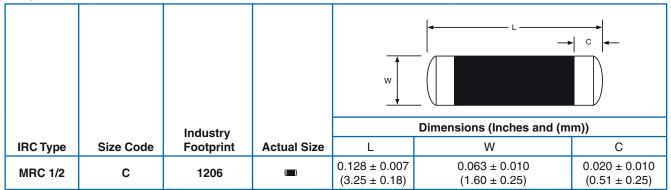
Environmental Data

| Characteristics | Maximum Change | Test Method | | |
|--------------------------------|--|--|--|--|
| Temperature Coefficient | As specified | MIL-R-55342E Par 4.7.9 (-55°C + 125°C) | | |
| Thermal Shock | ±(0.5% + 0.01Ω) | MIL-R-55342E Par 4.7.3 (-65°C + 150°C, 5 cycles) | | |
| Low Temperature Operation | ±(0.25% + 0.01Ω) | MIL-R-55342E Par 4.7.4 (-65°C @ working voltage) | | |
| Short Time Overload | ±(1.0% + 0.01Ω) | MIL-R-55342E Par 4.7.5 2.5 x √PxR for 5 seconds | | |
| High Temperature Exposure | ±(0.5% + 0.01Ω) | MIL-R-55342E Par 4.7.6 (+150°C for 100 hours) | | |
| Resistance to Bonding Exposure | ±(0.25% + 0.01Ω) | MIL-R-55342E Par 4.7.7 (Reflow soldered to board at 260°C for 10 seconds) | | |
| Solderability | 95% minimum coverage | MIL-STD-202, Method 208 (245°C for 5 seconds) | | |
| Moisture Resistance | ±(0.5% + 0.01Ω) | MIL-R-55342E Par 4.7.8 (10 cycles, total 240 hours) | | |
| Life Test | ±(1.0% + 0.01Ω) | MIL-R-55342E Par 4.7.10 (2000 hours @ 70°C intermittent) | | |
| Terminal Adhesion Strength | $\pm (1\% + 0.01\Omega)$ no mechanical damage | 1200 gram push from underside of mounted chip for 60 seconds | | |
| Resistance to Board Bending | $\pm (1\% + 0.01\Omega)$ no mechanical damage | Chip mounted in center of 90mm long board, deflected 5mm so as to exert pull on chip contacts for 10 seconds | | |

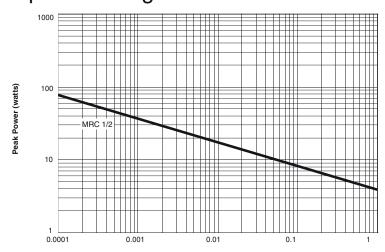
OBSOLETE



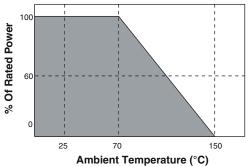
Physical Data



Repetitive Surge Curve



Power Derating Curve



Surge or Pulse Duration (seconds)

Note: Use for repetitive pulses where the average power dissipation is not to exceed the component rating at 70°C . Surge handling capacity for low-repetitive surges may be significantly greater than shown above. Contact factory for recommendations.

Ordering Data

